

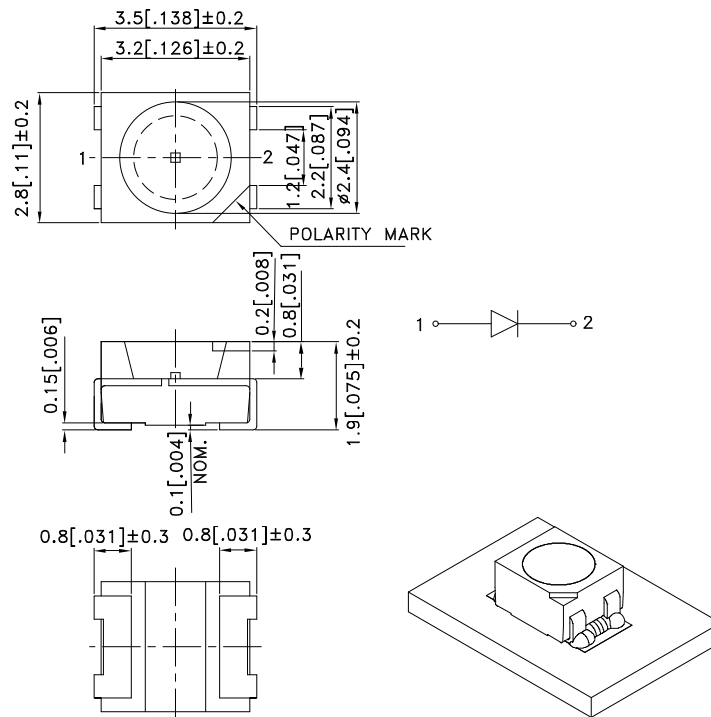
Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE : 1500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with In-GaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KA-3528ASURC	Hyper Red (InGaAlP)	WATER CLEAR	110	230	120°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Hyper Red	640		nm	I _F =20mA
λ _D [1]	Dominant Wavelength	Hyper Red	628		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Hyper Red	27		nm	I _F =20mA
C	Capacitance	Hyper Red	45		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Hyper Red	1.9	2.5	V	I _F =20mA
I _R	Reverse Current	Hyper Red		10	uA	V _R =5V

Notes:

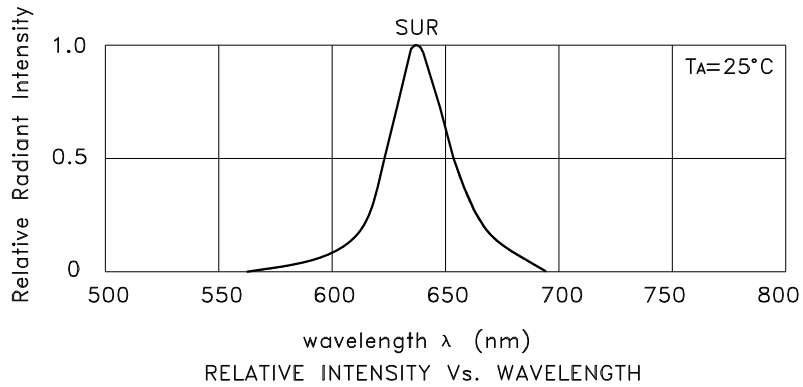
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units
Power dissipation	125	mW
DC Forward Current	50	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

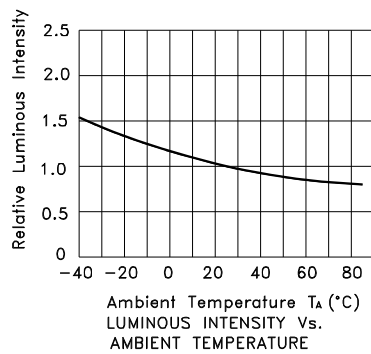
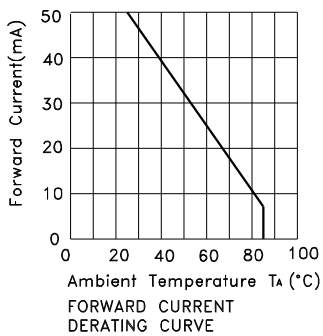
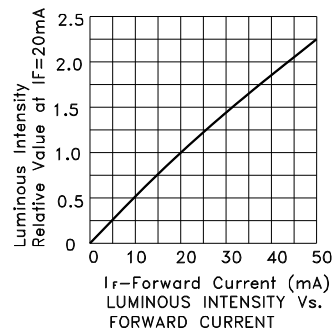
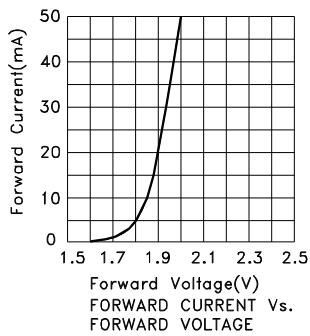
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Hyper Red

KA-3528ASURC



KA-3528ASURC

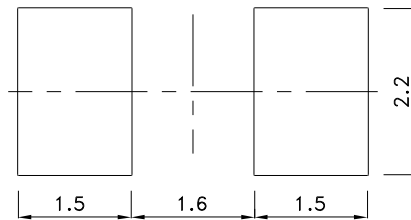
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Tape Specifications (Units : mm)

